

DERWENT-ACC-NO: 2003-321057

DERWENT-WEEK: 200331

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TITLE: Laminated ceramic capacitor manufacture  
involves plating external electrode using nickel and tin, after  
completion of baking process using electroconductive paste  
containing copper

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PRIORITY-DATA: 2001JP-243722 (August 10, 2001)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE
JP 2003059758 A	February 28, 2003	JA

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO
APPL-DATE		
JP2003059758A	N/A	2001JP-243722
August 10, 2001		

INT-CL-CURRENT:

TYPE	IPC	DATE
CIPP	H01G4/12	20060101
CIPS	H01G4/30	20060101

ABSTRACTED-PUB-NO: JP 2003059758 A

BASIC-ABSTRACT:

NOVELTY - The external electrode (3) is subjected to nickel plating and tin plating, after being baked using electroconductive paste containing base metal such as copper in non-oxidizing atmosphere.

USE - For manufacturing laminated ceramic capacitor.

ADVANTAGE - Prevents oxidation of electrode layer during baking

process and  
improves electrical connection property of the capacitor.

DESCRIPTION OF DRAWING(S) - The figure shows a sectional drawing of  
the  
laminated ceramic capacitor manufactured by external electrode.

external electrode (3)

CHOSEN-DRAWING: Dwg.1/4

TITLE-TERMS: LAMINATE CERAMIC CAPACITOR MANUFACTURE PLATE EXTERNAL  
ELECTRODE

NICKEL TIN AFTER COMPLETE BAKE PROCESS ELECTROCONDUCTING  
PASTE  
CONTAIN COPPER

DERWENT-CLASS: L03 V01

CPI-CODES: L03-B03E; L03-B03G;

EPI-CODES: V01-B03A; V01-B03C3A; V01-B03D1;

SECONDARY-ACC-NO:

CPI Secondary Accession Numbers: 2003-084197

Non-CPI Secondary Accession Numbers: 2003-256266